

CALOROC for SiPM readout

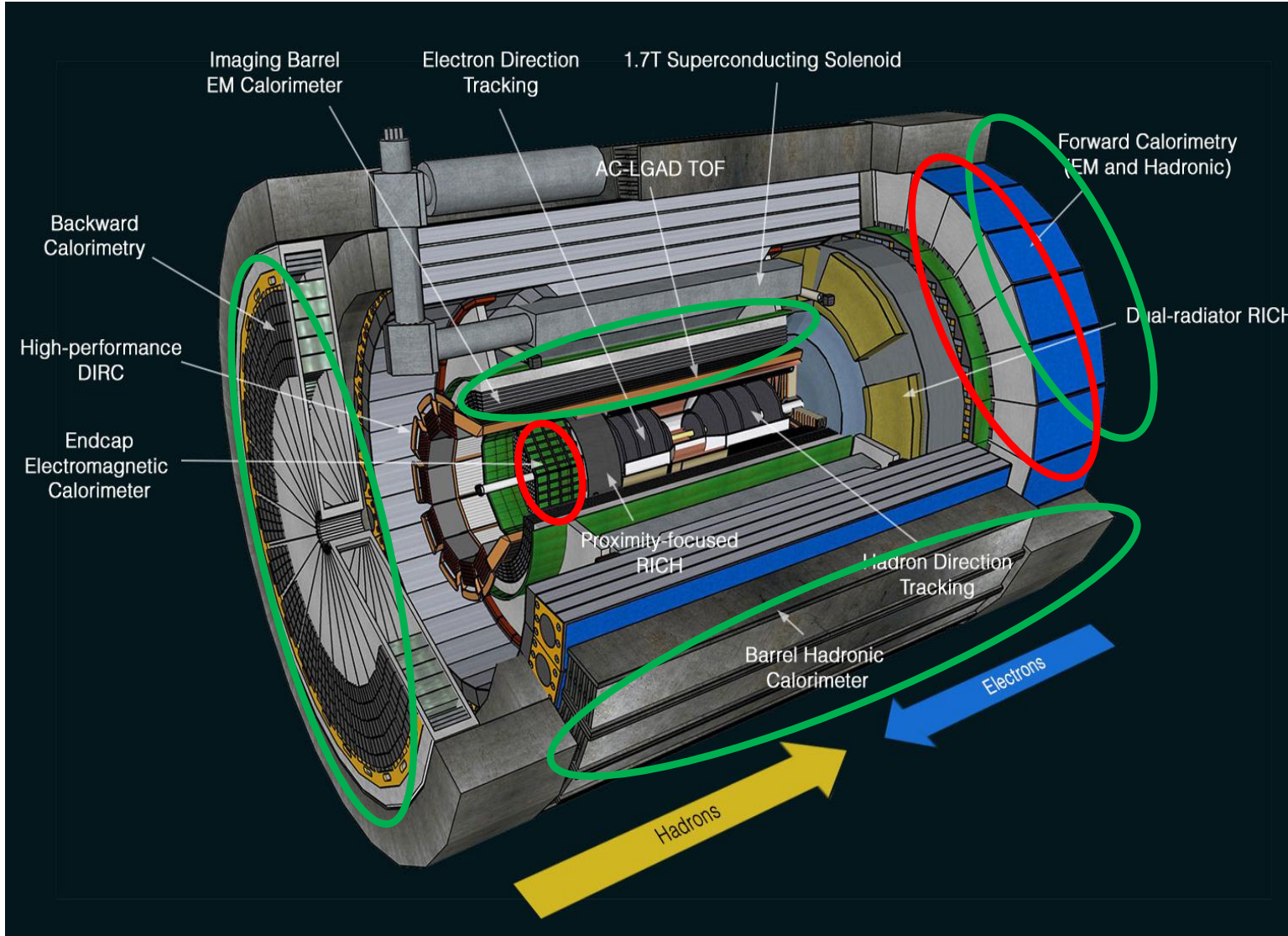
EIC calorimetry



ASIC Meeting - France
2-3 June 2025

Frederic DULUCQ



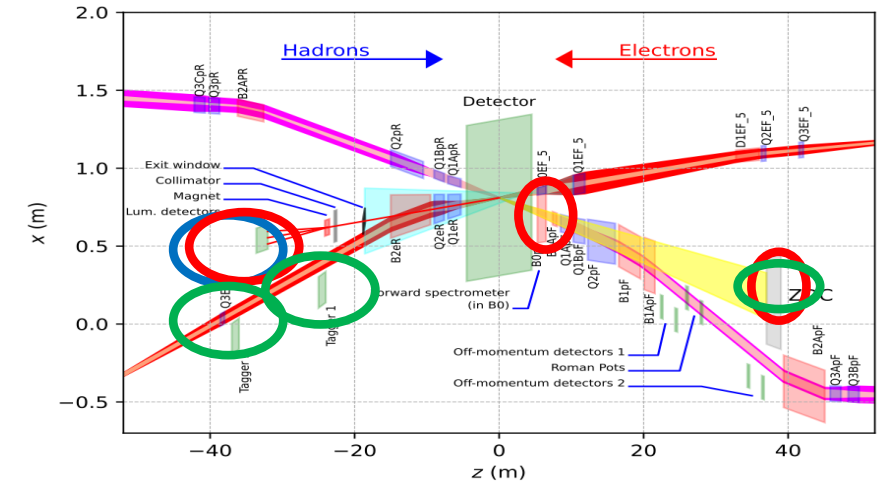


13 Calorimeters:

7 x SiPM – CALOROC

5 x SiPM – Discrete

1 x SiPM – Commercial fADC250



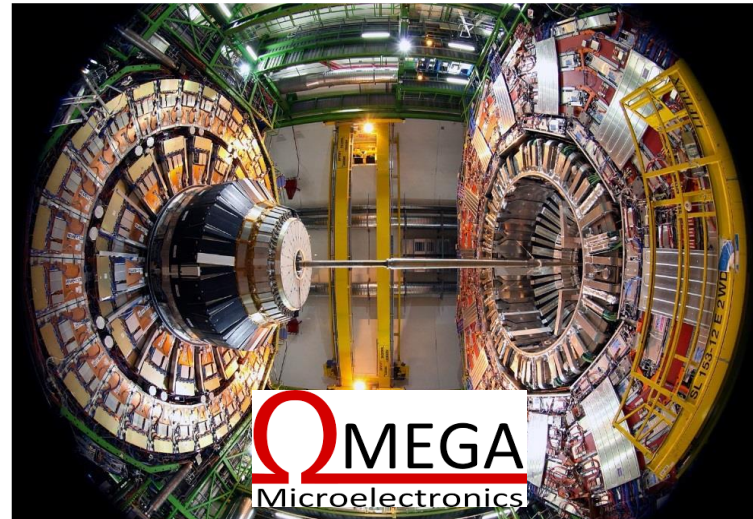
From J. Landgraf

H2GCROC for the endcap calorimeter – Phase II

6M of Silicon channels
(+ 240k of SiPM)

Radhard (200 Mrad)
Low Power (15 mW per chn)
Precise timing (25 ps)

Total of 150k ASICs needed
Pre-prod this year



CALOROC for EIC

Same ASIC structure (floorplan)
Same ADC and TDC
Same readout

Common interfaces

HEP trend => imaging calorimetry

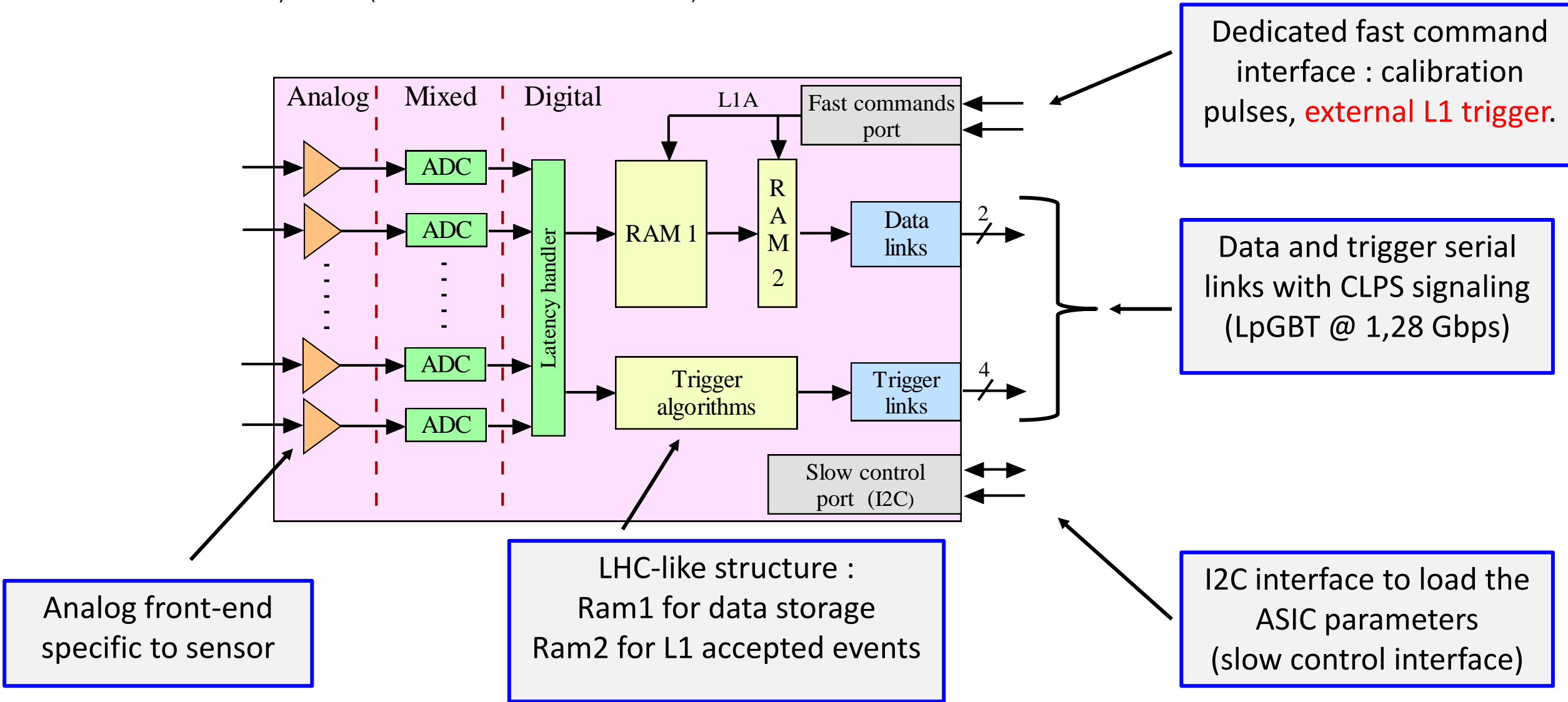
- High number of channels
- Charge and precise timing (<100 ps)
- Low power + System-On-Chip

Based on H2GCROC, CALOROC will provide a versatile and low-power solution for SiPM readout

ROC chips standard structure

❑ H2GCROC (for SiPM readout) is an HL-LHC colored ASICs (external L1 trigger)

❑ Below is an calorimetry structure (but interfaces for CALOROC will be similar)



❑ CALOROC will be available in 2 versions for SiPM readout:

- ❑ SiPM range capacitance from 500 pF to 10 nF
- ❑ ~ 10-15 mW / channel
- ❑ Radiation hardening (HL-LHC levels)
 - ❑ 200 Mrad and 10^{16} n_{eq} / cm^2 (1 MeV equivalent neutrons)
 - ❑ SEE hardening on control logic
- ❑ Charge and time measurement

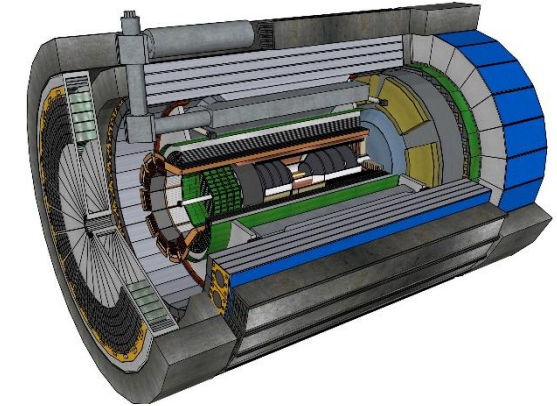
❑ Streaming readout (no external trigger required)

❑ Conservative CALOROC1A based on CMS H2GCROC:

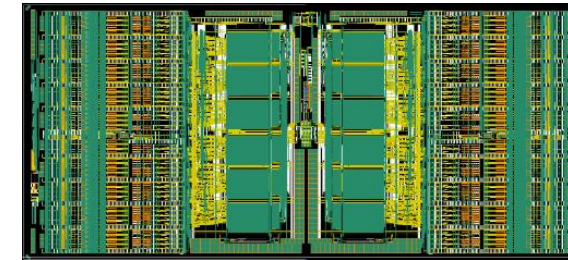
- ❑ H2GCROC (ADC, TOT) analog/mixed reuse
- ❑ Back-end compatible with EIC + zero-suppress

❑ New CALOROC1B based on gain switching:

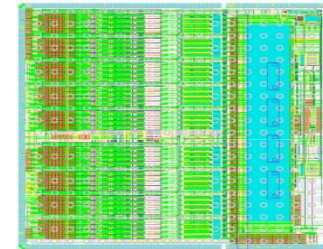
- ❑ New analog part without TOT (dynamic gain switching)
- ❑ Backend « à la HKROC »: auto-trigger, zero-suppress – EIC compatible



HGCROC



HKROC

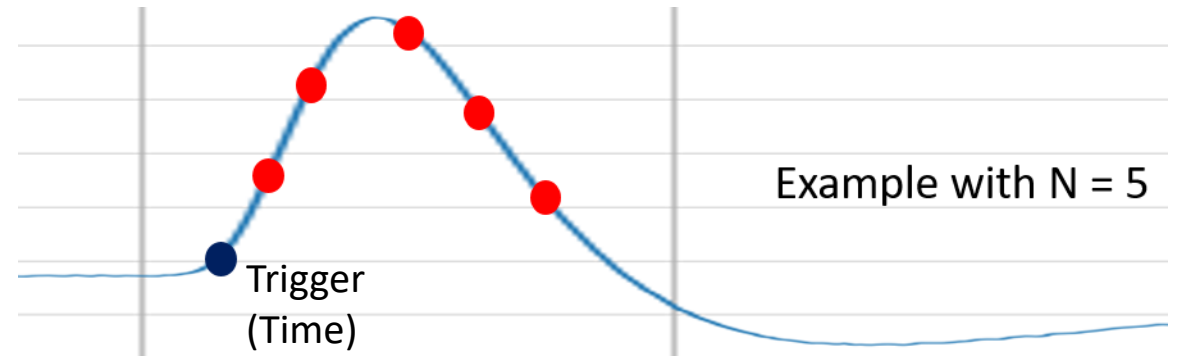


CALOROC 1A
CMS front end
EIC readout

CALOROC 1B
New front end
EIC readout

CALOROCs will share a common backend
+ pin-pin compatibility

- ❑ CALOROC is a waveform digitizer working @ 39.4 MHz
 - ❑ Number of charge sampling points from 1 to 7
 - ❑ Fast channel for precise timing (25 ps binning)
 - ❑ Charge reconstruction algorithm is outside (back-end or offline)



CALOROC can accept ~ 50 kHz rate per channel

Internal HKROC memory writing is without dead time
Hit-rate is only limited by serial link bandwidth (average values above)

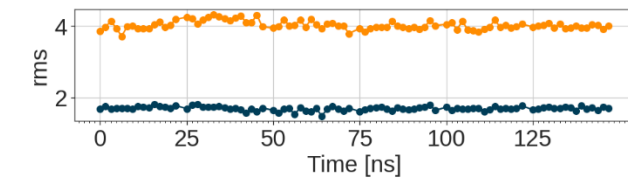
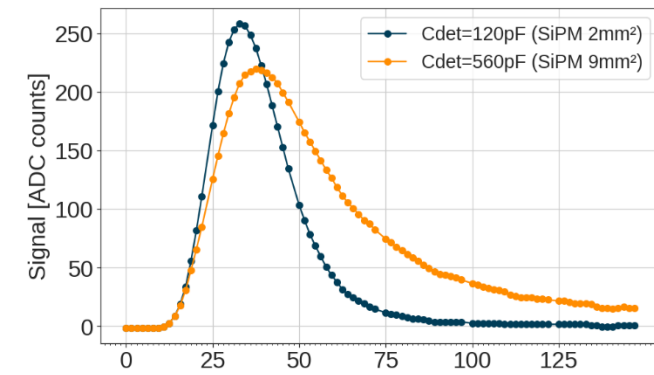
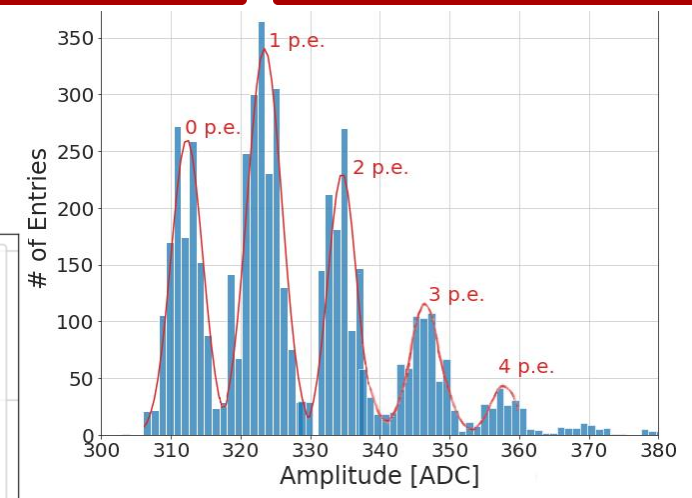
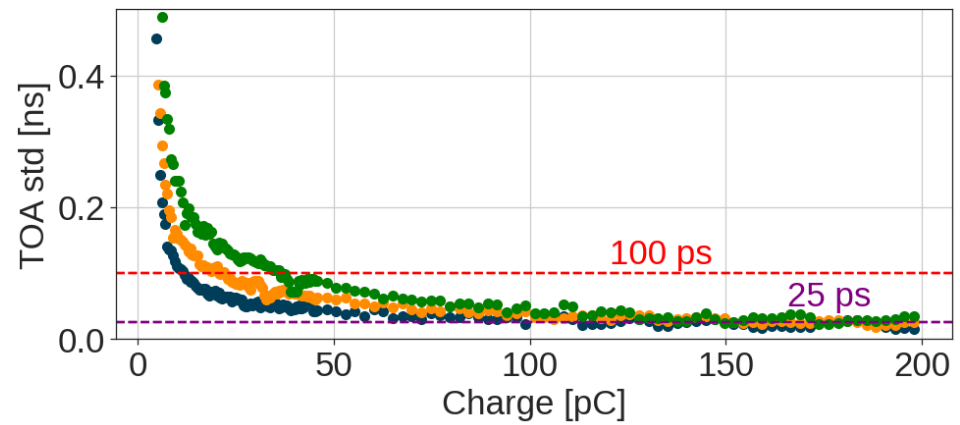
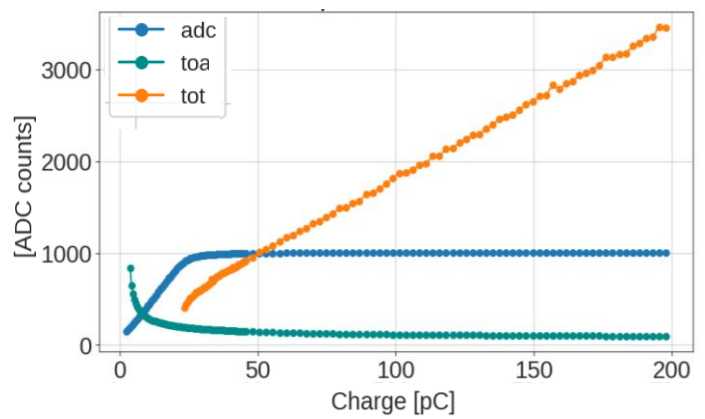
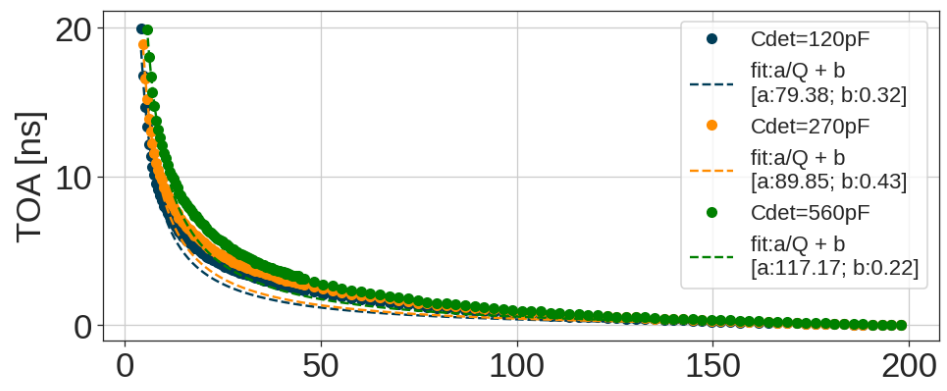
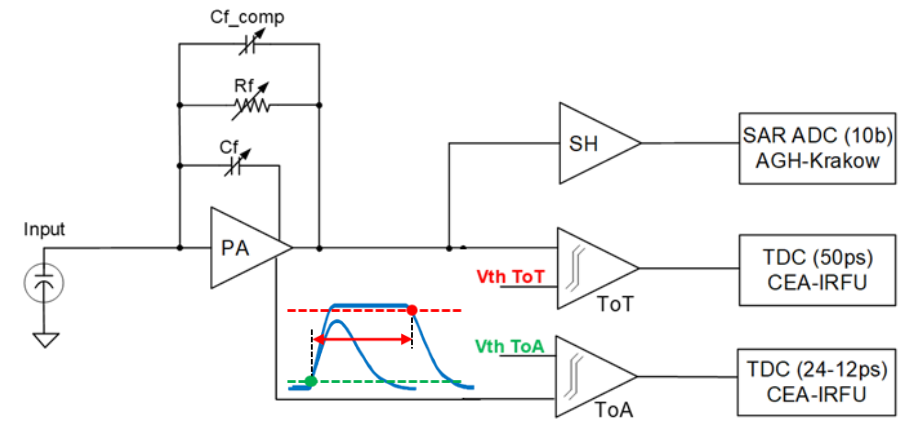
A zero-suppress feature can be activated or not

A fast command can trigger an ASIC snapshot
(monitoring, calibration, heartbeat)

CALOROC1A (based on H2GCROC)

☐ Reuse of analog front-end based on ADC/TOT and TOA: fully characterized *

☐ 15 mW per channel / Radiation performance / SiPM range 100-600 pF



☐ CALOROC1A will only update its back-end to be EIC compatible

* TWEPP 2023 → <https://doi.org/10.1088/1748-0221/19/04/C04005>

CALOROC1B: Chosen architecture

❑ New dynamic frontend with switched gain:

- ❑ High gain
- ❑ 2x medium gain
- ❑ Low Gain

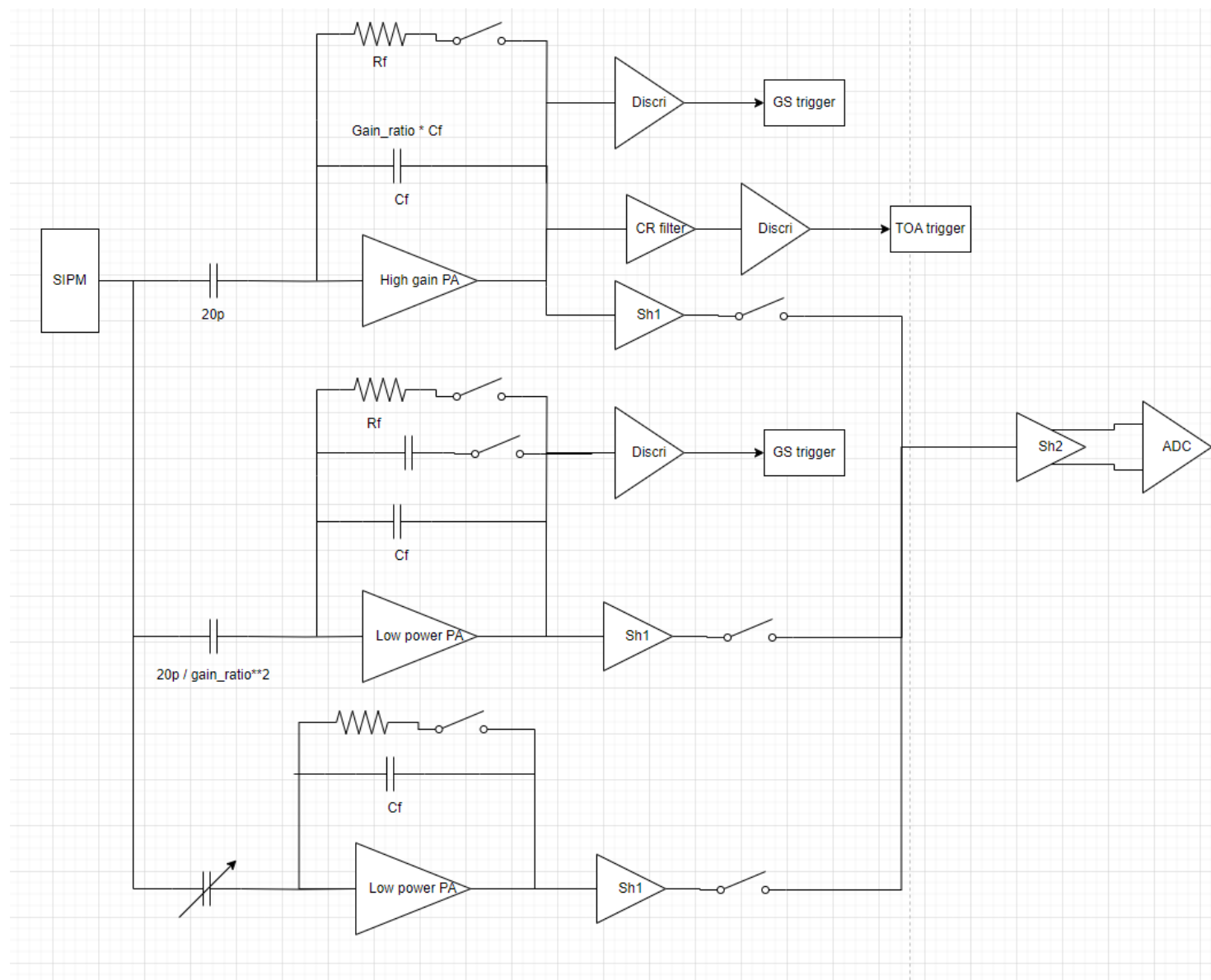
❑ Reuse CMS-H2GCROC ADCs and TDCs:

- ❑ 10-bit 40 MHz ADC (Krakow)
- ❑ 25 ps TDC (Saclay)

❑ Shared CALOROCs backend

❑ Common specifications:

- ❑ SiPM from 500 pF to 2.5 - 10 nF
- ❑ ~ 10-15 mW/channel
- ❑ CMS HL-LHC Radiation level 200 Mrad



- ❑ The SiPM configuration has a direct impact on the SNR
 - ❑ SNR for 1p.e is proportional to Q/C (larger SiPM cap decrease SNR)
 - ❑ Gain of $1.8e5$ electrons per p.e (table below)

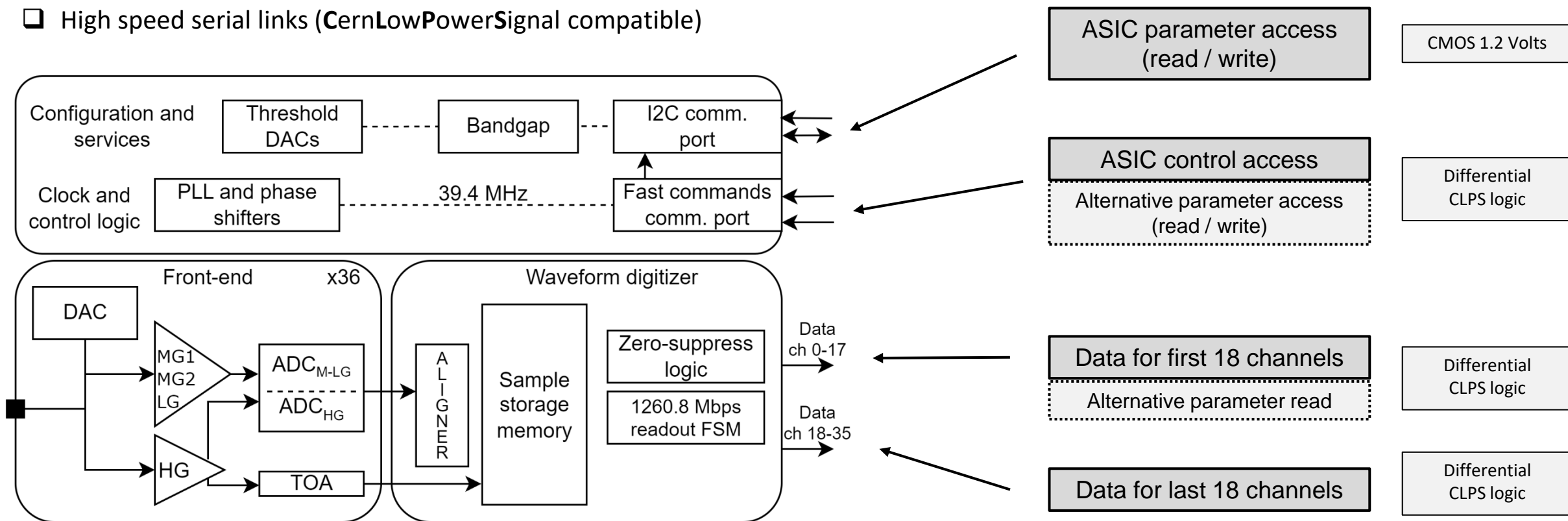
- ❑ CALOROC1b will be able to readout SiPM in the range ~ 500 pF to 10 nF
 - ❑ Timing measurements will focus on the MIP ($\sim 15pe$)

Operation modes	1 SiPM of 530pF Caloroc1B	1 SiPM of 2.5nF Caloroc1B	4 SiPM of 2.5nF Caloroc1B	1 SiPM of 530pF Caloroc1A
Cin	530pF	2.5nF	10nF	560pF
Dynamic range in charge (Noise - Max)	2.6fC-190pC	12fC-770pC	48fC-3.1nC	20fC-320pC
Input time constant (occupancy related)	100ns	500ns	500ns	10ns
Jitter @ MIP ($\approx 400fC$)	35ps	110ps	470ps	400ps
SNR @ 1p.e ($\approx 30fC@gain=1.8e5$)	10	2.4	0.6	1.44

CALOROCs: block diagram and interfaces

❑ CALOROCs will have the same interfaces (comparable to CMS ones):

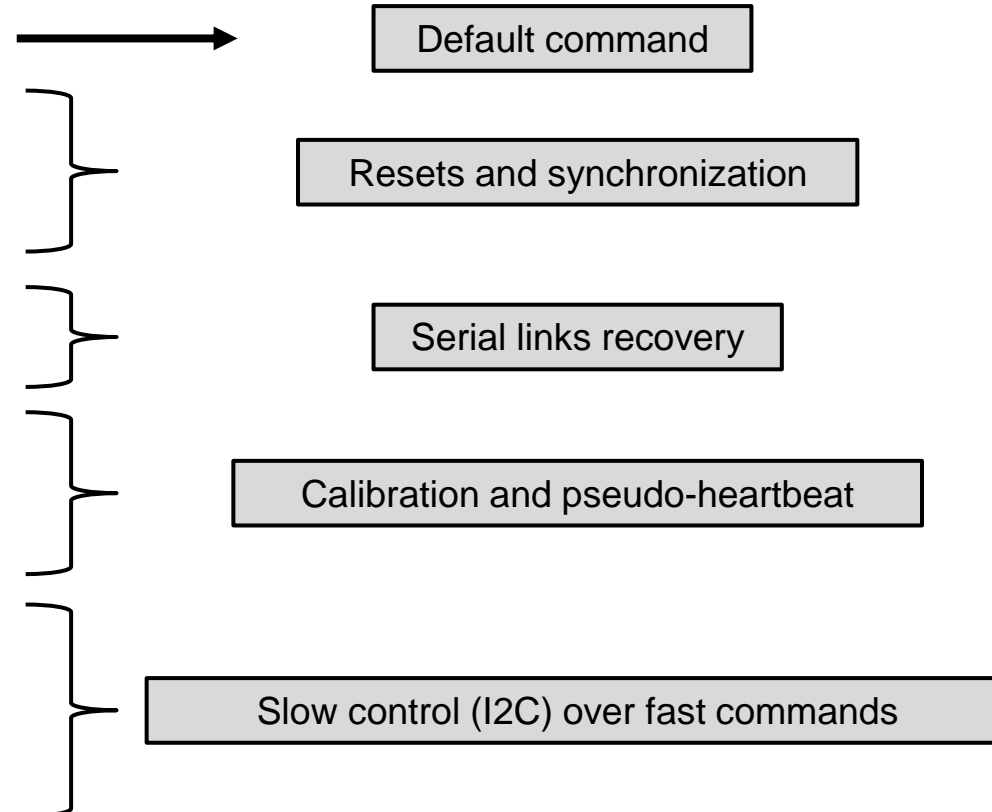
- ❑ 1 clock @ 315,2 MHz + 2 resets (hard + soft)
- ❑ Fast command to dynamically control the ASIC (differential)
- ❑ I2C to set the parameters (tbc)
- ❑ High speed serial links (**CernLowPowerSignal** compatible)



CALOROC fast commands

- ❑ Commands to interact dynamically with the ASIC
 - ❑ 8 bits commands synchronized with incoming 315,2 MHz clock – MSB first
 - ❑ Only Idle really needed – others have a known latency
 - ❑ Detailed in the datasheet

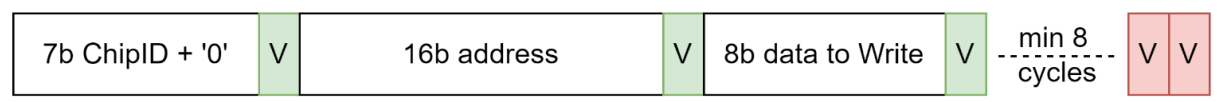
Fast commands	Value	Description
Idle	00110110	Default command inside
ChipSync	11010010	Reset FSM, buffers and counters
BCR	00011101	Reset timestamp counter to a default value
EBR	11010001	Empty readout buffers
LinkResetROCD	10011010	Transmission of synchronization patterns
ROC-Serializer-Reset	10011100	Reset serializer link module only
L1A	01001011	External trigger (all channels)
CalPulseInt	00101101	800 ns internal calibration pulse
CalPulseExt	01111000	100 ns external calibration pulse
SC_0	01011010	Send bit 0 to SLIM
SC_1	01011100	Send bit 1 to SLIM
SC_Valid_Reset	10001011	Send validation to SLIM or a reset transaction (2 consecutives)



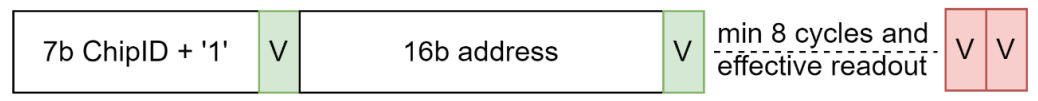
Slow control – parameter access through fast command

- ❑ New feature to read/write parameter through fast command
 - ❑ I2C is still the default way to access ASIC parameters
 - ❑ Uses 3 dedicated fast command to “recreate” I2C frames
 - ❑ Main advantages: x40 speed + use existing serial links
 - ❑ Detailed in the datasheet

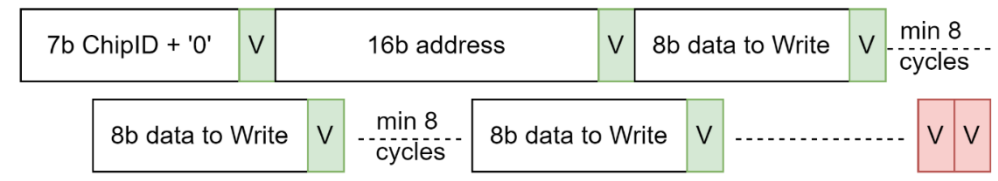
Simple write action



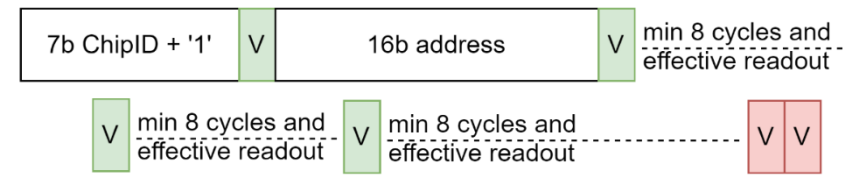
Simple read action



multibyte write



multibyte read



Read through high speed link

4b-data Header	2b Mode	Dh	16b I2C address	8b data	1
Idle/Sync Header	28b default IDLE Pattern				

Slow control – parameter access through I2C

- ❑ Use existing CERN module (used in ALTIROC)
 - ❑ I2C is the default way to access parameters
 - ❑ Max 1 MHz speed and 30 address available (+1 broadcast)
 - ❑ Detailed in the datasheet

S / P: START and STOP condition of a standard I2C protocol

CHIP ADDR: 7-bit chip address (MSB must be set to 1)

SUB-ADR [15:8]: sub-block (cluster) number (from 0 to 255)

SUB_ADR [7:8]: register number (from 0 to 31) – not used bits must be set to 0

DATA[7:0]: data to be written in the parameter

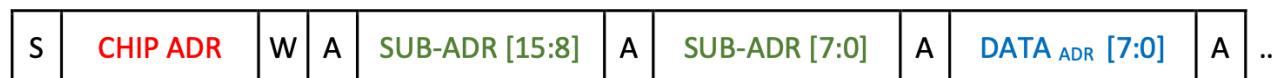
A: Acknowledge bit



Default write



Default read



Multibyte
write



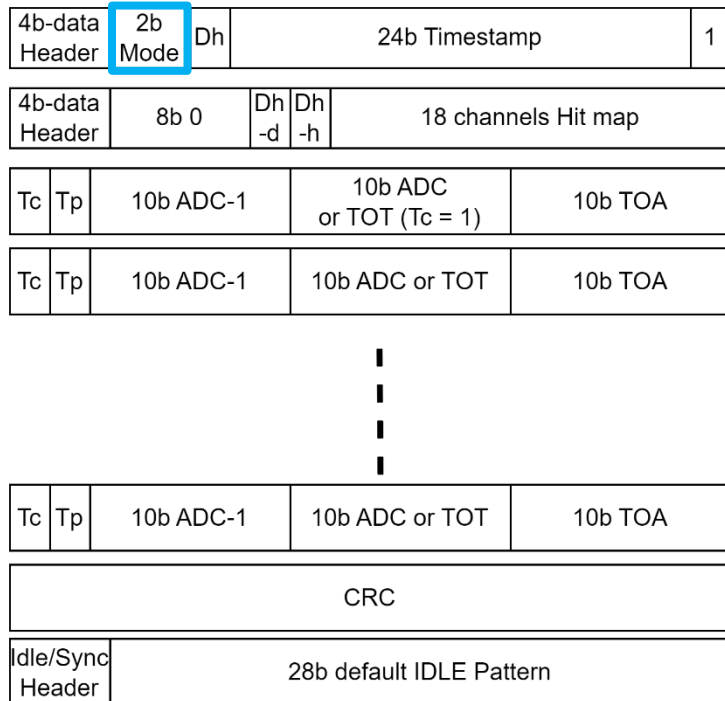
Multibyte
read



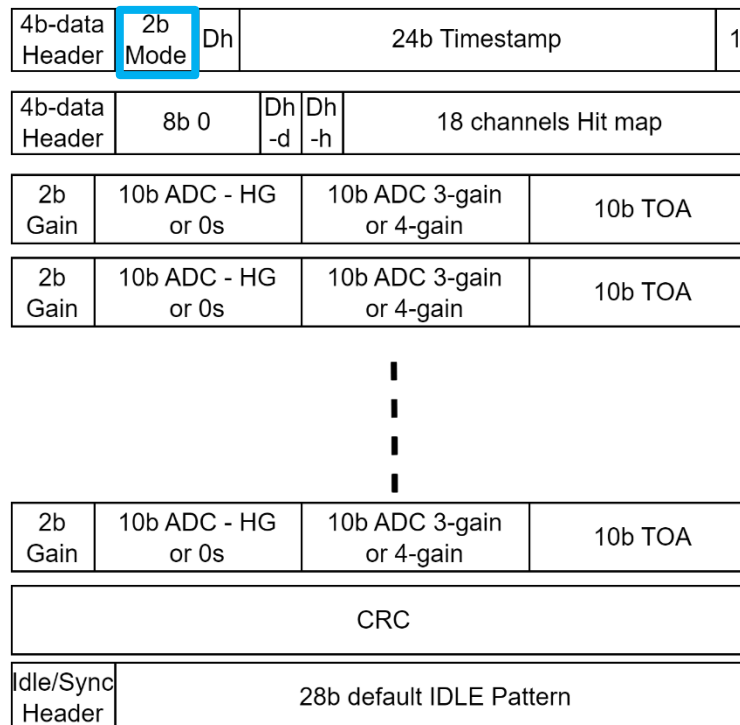
EIC: CALOROC readout frames

For charge measurements, CALOROC-A based on ADC/TOT, CALOROC-B only ADCs

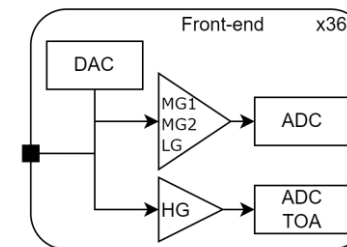
CALOROC A (CMS-like)



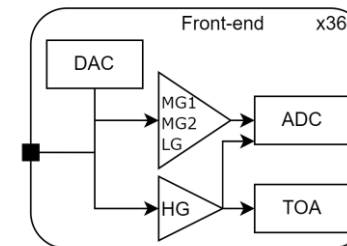
CALOROC B – 2 ADCs or 1 ADC (4 gains)



CALOROC B (2 ADCs)



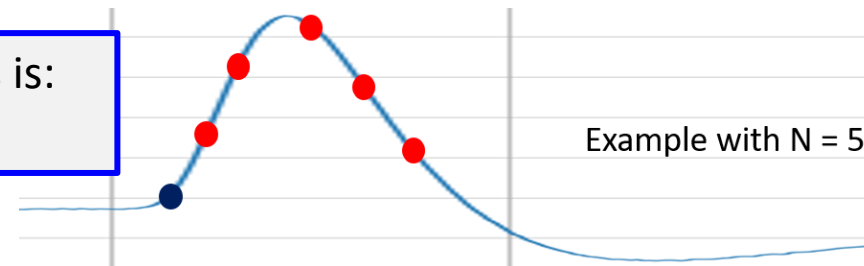
CALOROC B (1 ADCs)



In ZS mode, for **X** (1-18) hit channels and **N** samples, number of 32-bit words is:

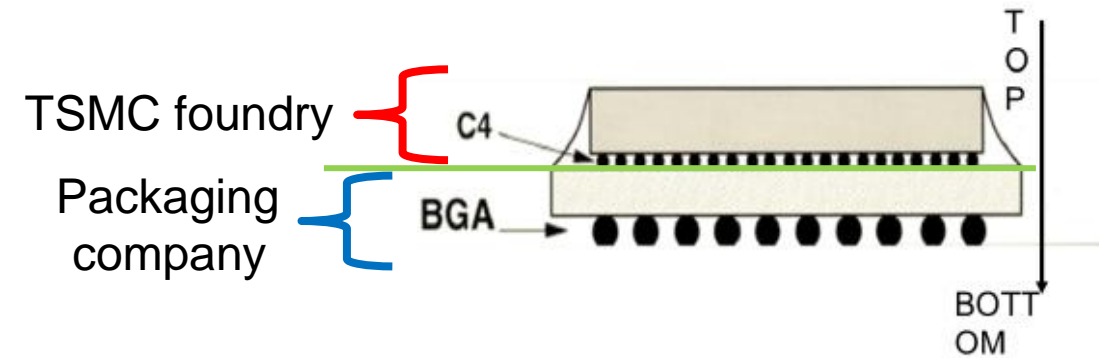
$$N \times (2\text{Headers} + X + 2\text{Trailers})$$

In characterization mode, forced TcTp, ADC, TOT, TOA for all channels



□ CALOROC will have the same package as the existing HKROC:

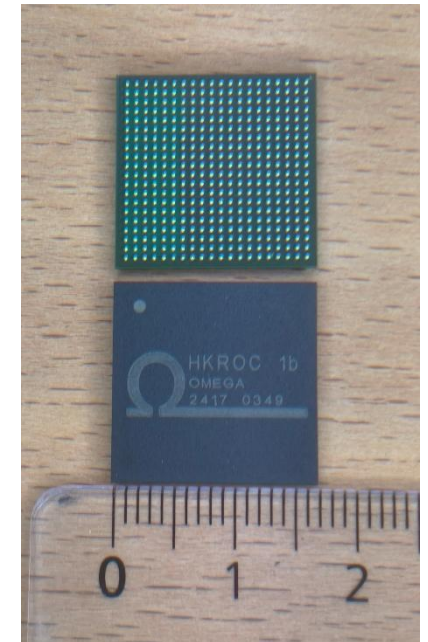
- JEDEC MO-216 – 17 x 17 mm BGA version
- 400 balls with 0,8 mm pitch
- Specific substrate (interposer) designed at OMEGA
- **QR code** like HGCROC3



JEDEC SOLID STATE PRODUCT OUTLINE	TITLE: THIN PROFILE, SQUARE AND RECTANGULAR, BALL GRID ARRAY FAMILY, 1.00 & 0.80 mm PITCHES	ISSUE: E	DATE: AUG 2003	MO-216
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TABLE 3: SQUARE VARIATIONS – 0.80 PITCH

D / E	e = 0.80							
	MD/ME	N	SD/SE	VARIATION	MD-1/ME-1	N	SD/SE	VARIATION
14.00	17	289	0.00	BAJ-1	16	256	0.40	BAJ-2
15.00	18	324	0.40	BAK-1	17	289	0.00	BAK-2
16.00	19	361	0.00	BAL-1	18	324	0.40	BAL-2
17.00	20	400	0.40	BAM-1	19	361	0.00	BAM-2



❑ CALOROC will have the same package as existing HKROC:

- ❑ ~10 signals needed to control CALOROC (4 diff + 6 single)
- ❑ Around 350 pins for power/static/bias
- ❑ Detailed in the datasheet

Pin type	# balls (variant)
GND	175
VDD	102
BIAS / static / debug	37 (-2+0)
Not connected	36 (-0+2)
Analog inputs	36
Controls	14 (-2+2)



MAPPING CALOROC_1 BGA 400 (TOP VIEW)

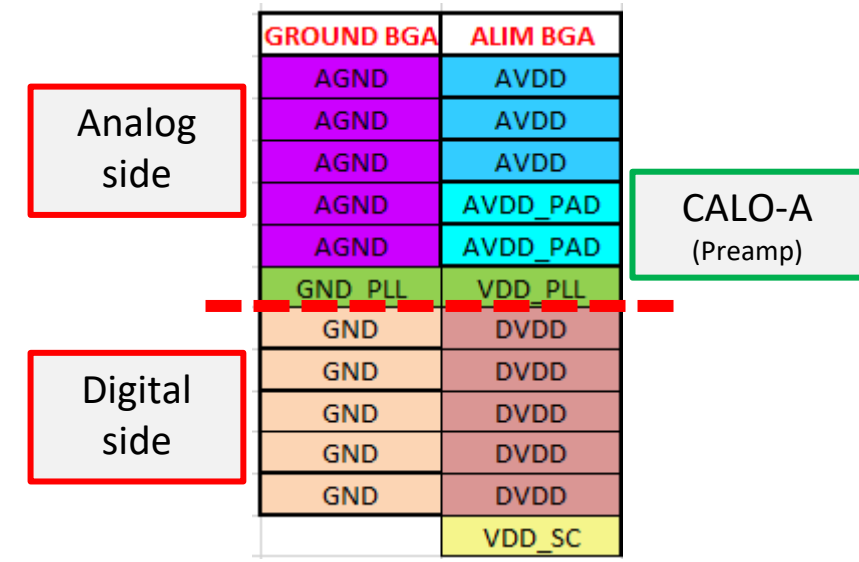
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
SDA	RSTB_I2C	HARD_RSTB	SOFT_RSTB	ERROR	CK_320_N	CK_320_P	FCMD_P	FCMD_N	ADD<4>	CHIP_R	AGND	AVDD	AGND	AGND	AGND	AGND	AGND	AGND	AGND
SCL	GND	GND	GND	GND	GND	VHI10<0>	VHI10<1>	FLAG_AF	ADD<4>	VREF_ADC	AGND	AVDD	AGND	IN<0>	AGND	IN<1>	AGND	NC	VDDA_PAD
DAC_ALDO	GND	GND	GND	GND	GND	NC	NC	FLAG_AF	NC	VCM_ADC	AGND	AVDD	AGND	IN<2>	AGND	IN<3>	AGND	NC	VDDA_PAD
NC	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<4>	AGND	IN<5>	AGND	NC	VDDA_PAD
NC	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<6>	AGND	IN<7>	AGND	NC	VDDA_PAD
OUT_TSPFF	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<8>	AGND	IN<9>	AGND	AGND	AGND
SIPM_CALIB	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<10>	AGND	IN<11>	AGND	NC	VREF_SK_LP
NC	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<12>	AGND	IN<13>	AGND	AGND	AGND
STROBE_EXT	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<14>	AGND	IN<15>	AGND	NC	VREF_NOINV_SK
EFUSE	NC	GND	DVDD	VDD_PLL	VDD_PLL	AGND_PLL	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<16>	AGND	IN<17>	AGND	NC	VREFINV_VBM3PA
TRIG_P	NC	GND	DVDD	VDD_SC	VDD_SC	AGND_PLL	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<18>	AGND	IN<19>	AGND	NC	VREFTOA_VBIPA
TRIG_N	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<20>	AGND	IN<21>	AGND	NC	VREFTOT_VBMPA
DAQ2_P	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<22>	AGND	IN<23>	AGND	NC	VBG_1V
DAQ2_N	PLL_LOCK	GND	DVDD	VDD_SC	VDD_SC	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<24>	AGND	IN<25>	AGND	NC	PROBEPA_VBOPA
DAQ3_P	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<26>	AGND	IN<27>	AGND	NC	INCTEST
DAQ3_N	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<28>	AGND	IN<29>	AGND	NC	VDDA_PAD
ADD<3>	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AVDD	AVDD	AVDD	AGND	IN<30>	AGND	IN<31>	AGND	NC	VDDA_PAD
ADD<2>	GND	GND	GND	GND	GND	NC	NC	NC	NC	VCM_ADC	AGND	AVDD	AGND	IN<32>	AGND	IN<33>	AGND	NC	VDDA_PAD
ADD<1>	GND	GND	GND	GND	GND	NC	VHI10<2>	NC	NC	VREF_ADC	AGND	AVDD	AGND	IN<34>	AGND	IN<35>	AGND	NC	VDDA_PAD
ADD<0>	PROBE_TOT_PA	PROBE_TOA	PROBE_DC2	PROBE_DC1	PROBE_INV	VNEG	VHI10<3>	PROBE_NOINV	TRIG2_EXT	TRIG1_EXT	AGND	AVDD	AGND	AGND	AGND	AGND	AGND	AGND	AGND

CALOROC integration and power supply consideration

- On the board, CALOROC will need a maximum of 3 power supplies:
 - Analog / Digital + 1 dedicated for CALOROC-A (Preamp)
 - (Not shown here: LED power and HV)

MAPPING CALOROC_1 BGA 400 (TOP VIEW)

Digital side										Analog side									
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
SDA	RSTB_I2C	HARD_RSTB	SOFT_RSTB	ERROR	CK_320_N	CK_320_P	FCMD_P	FCMD_N	AD<4>	CHIP_R	AGND	AVDD	AGND	AGND	AGND	AGND	AGND	AGND	AGND
SCL	GND	GND	GND	GND	GND	VH10<0>	VREF_ADC	FLAG_AF	AD<4>	VREF_ADC	AGND	AVDD	AGND	IN<0>	AGND	IN<1>	AGND	NC	VDDA_PAD
DAC_ALDO	GND	GND	GND	GND	GND	NC	NC	FLAG_AF	AD<4>	VCM_ADC	AGND	AVDD	AGND	IN<2>	AGND	IN<3>	AGND	NC	VDDA_PAD
NC	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<4>	AGND	IN<5>	AGND	NC	VDDA_PAD
OUT_TSPFF	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<6>	AGND	IN<7>	AGND	NC	VDDA_PAD
SIPM_CALIB	NC	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<8>	AGND	IN<9>	AGND	AGND	AGND
NC	NC	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AGND	AGND	AGND	AGND	AGND	IN<10>	AGND	IN<11>	AGND	NC	VREF_SK_LP
STROBE_EXT	NC	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	AGND	AGND	AGND	AGND	AGND	IN<12>	AGND	IN<13>	AGND	AGND	AGND
EFUSE	NC	GND	DVDD	VDD_PLL	VDD_PLL	AGND_PLL	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<14>	AGND	IN<15>	AGND	NC	VREF_NOINV_SK
TRIG_P	NC	GND	DVDD	VDD_SC	VDD_SC	AGND_PLL	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<16>	AGND	IN<17>	AGND	NC	VREFINV_VBM3PA
TRIG_N	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<18>	AGND	IN<19>	AGND	NC	VREFTOA_VBIPA
DAQ2_P	NC	GND	DVDD	DVDD	DVDD	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<20>	AGND	IN<21>	AGND	NC	VREFTOA_VBIPA
DAQ2_N	PLL_LOCK	GND	DVDD	VDD_SC	VDD_SC	GND	GND	GND	AGND	AGND	AGND	AGND	AGND	IN<22>	AGND	IN<23>	AGND	NC	VBG_IV
DAQ3_P	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<24>	AGND	IN<25>	AGND	NC	PROBEP_VBOPA
DAQ3_N	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<26>	AGND	IN<27>	AGND	NC	INCTEST
ADD<3>	GND	GND	DVDD	DVDD	DVDD	DVDD	DVDD	DVDD	D<0>	AVDD	AVDD	AVDD	AGND	IN<28>	AGND	IN<29>	AGND	NC	VDDA_PAD
ADD<2>	GND	GND	GND	GND	GND	NC	NC	NC	VCM_ADC	AGND	AVDD	AGND	AGND	IN<32>	AGND	IN<33>	AGND	NC	VDDA_PAD
ADD<1>	GND	GND	GND	GND	GND	NC	VH10<2>	NC	VREF_ADC	AGND	AVDD	AGND	AGND	IN<34>	AGND	IN<35>	AGND	NC	VDDA_PAD
ADD<0>	PROBE_TOT_PA	PROBE_TOA	PROBE_DC2	PROBE_DC1	PROBE_INV	VNEG	VH10<3>	PROBE_NOINV	TRIG1_EXT	TRIG1_EXT	AGND	AVDD	AGND	AGND	AGND	AGND	AGND	AGND	AGND



Board power	Nominal value	ASIC power	Max ratings
Analog power	1.2 Volts	AVDD, VDD_PLL	8 mW / chn
Preamp power	2.5 or 1.2 Volts (CALO-A or CALO-B)	AVDD_PAD	2 mW / chn
Digital power	1.2 Volts	DVDD	5 mW / cnn

Values will be refined after first measurements

❑ CALOROC characterization motherboard under design at OMEGA:

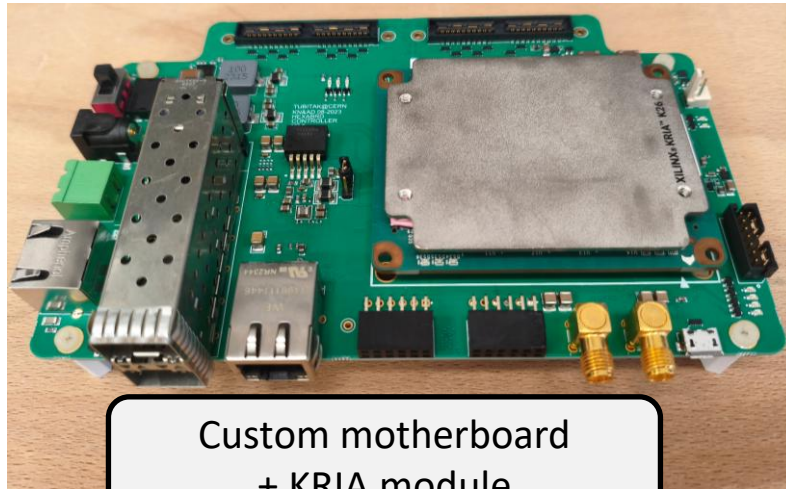
- ❑ Originally developed for HGCROC and the HKROC
- ❑ Well-known at OMEGA and LLR (firmware based only)
- ❑ Compatible with KRIA motherboard (CERN) but software + firmware needed

Python scripts

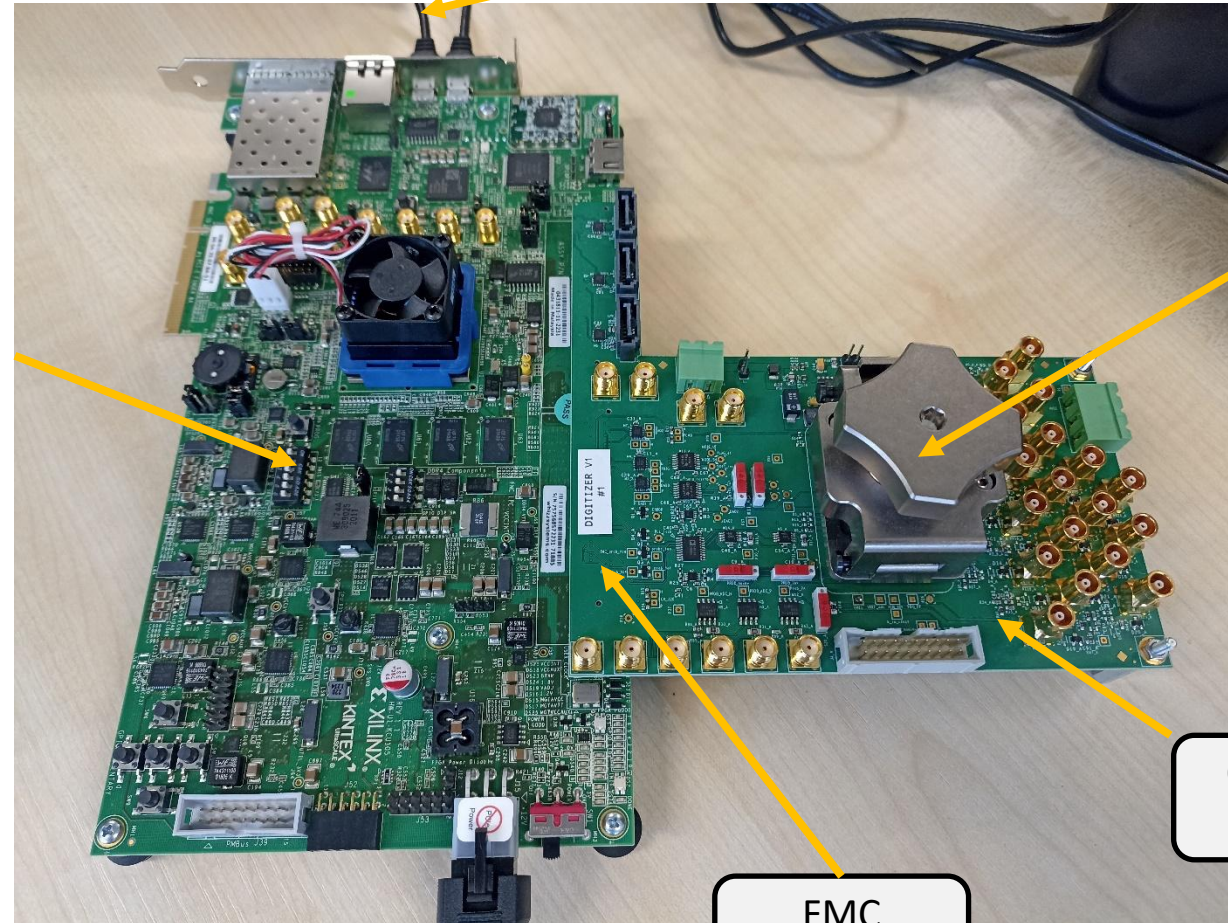


Monitor
Program
Test

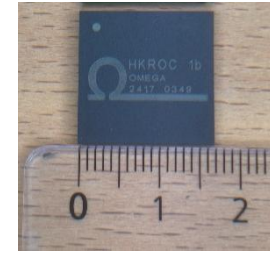
Commercial
KCU105 board



Custom motherboard
+ KRIA module



CALOROC
BGA socket

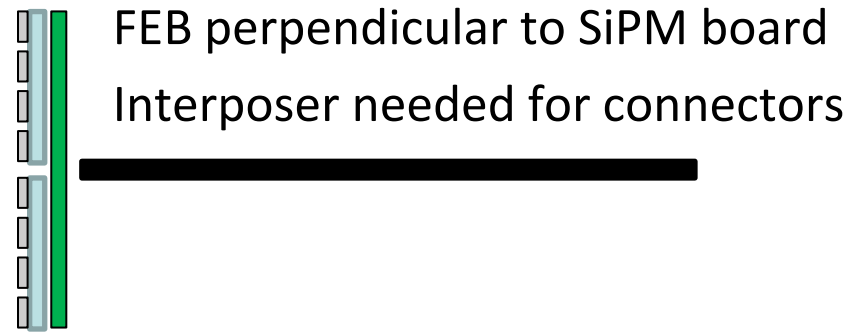
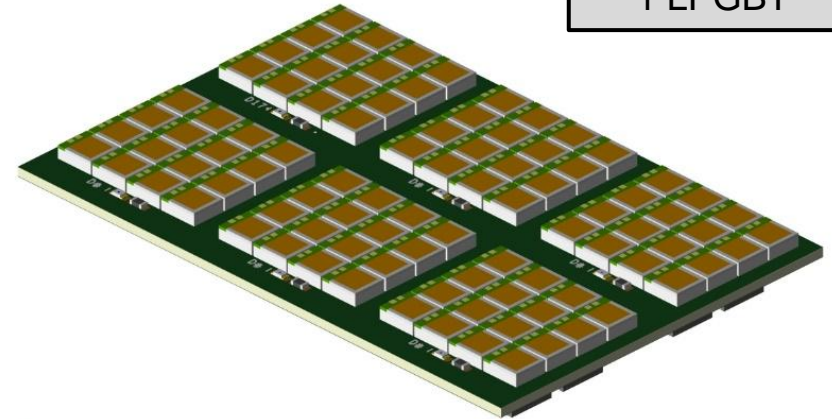


Custom CALOROC
motherboard

FMC
connector

- ❑ Try to find an optimum between CALOROC and LpGBT for the integration
 - ❑ Driven by serial links @ 1,26 Gbps
 - ❑ CALOROC: 2 serial links for data output (1,26 Gbps)
 - ❑ LpGBT has max 7 inputs (1,26 Gbps)

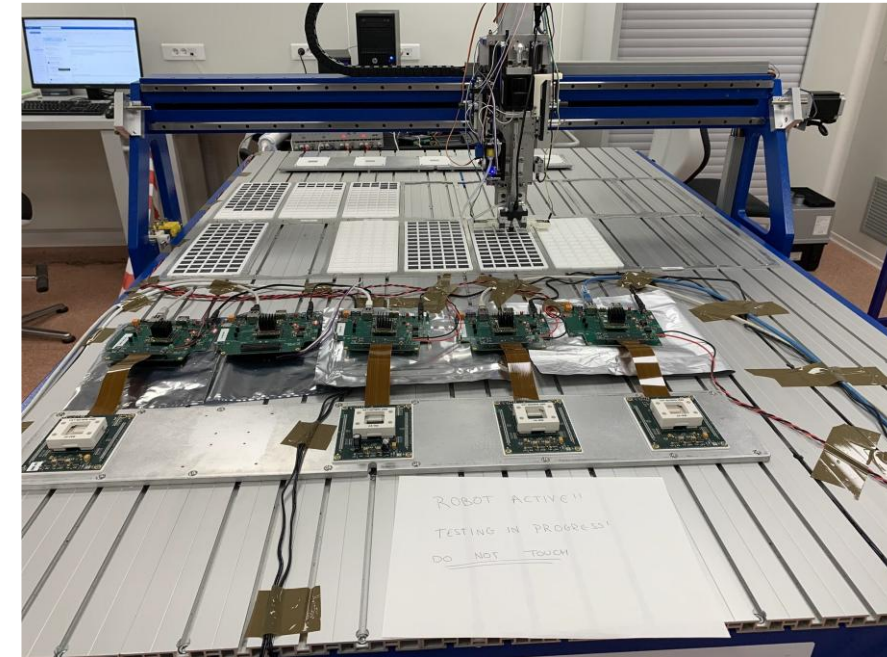
3 CALOROCs
+
1 LPGBT



Side view

ASIC # (usage)	1 (50%)	1 (100%)	3 (100%)
FEB width	18 mm	38 mm	38 or 58 mm
FEB length	~ not constrained	~ not constrained	~ not constrained
LpGBT # (usage)	1 (15%)	1 (30%)	1 (100%)
Remarks	Need smaller package ?		optimum

- ❑ Expertise in radiation-hardened front-end ASICs for HEP
 - ❑ HL-LHC ASICs: ATLAS HGTD and CMS HGCAI (10^5 ASICs)
- ❑ Expertise in irradiation testing (dose and displacement)
 - ❑ HL-LHC levels 200 Mrad and 10^{16} n_{eq} / cm^2 (1 MeV equivalent neutrons)
- ❑ Standard interfaces ensures a full compatibility with our robot
 - ❑ 2x 50 ASICs tested per hour (H2GCROC) with QR code scan
- ❑ CALOROC timeline – 2025 to 2028
 - ❑ Now: submission process start - CALOROCs submission (Eng. Run)
 - ❑ Oct 2025: first packaged ASICs back to the lab
 - ❑ 2 months to have an overall view of the performances
 - ❑ + 6 months for a deeper characterization
 - ❑ 2026-2027, irradiation campaigns
 - ❑ 2026: Decision for the final number of channels
 - ❑ Q1 2027: final submission (same channel count) + 2028 production
 - ❑ Schedule need to be refined if channels are doubled



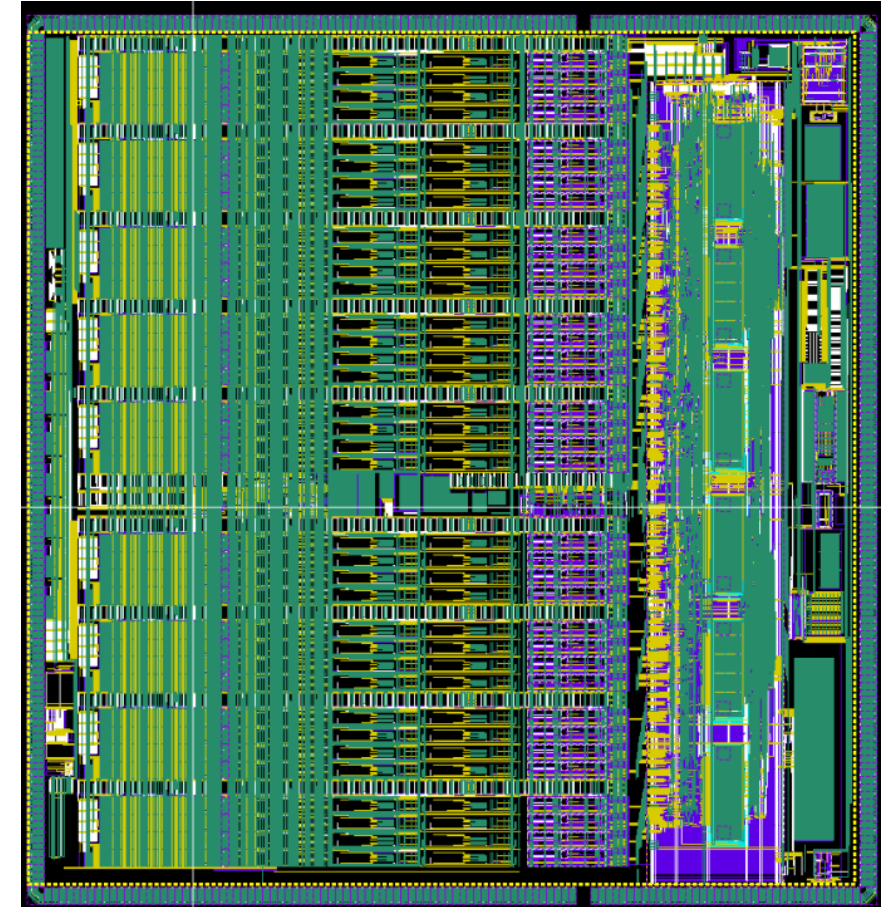
- ❑ Conservative **CALOROC-1A**:
 - ❑ Based on CMS SiPM H2GCROC with EIC readout

- ❑ New **CALOROC-1B**:
 - ❑ New analog front end
 - ❑ Higher dynamic range and input capacitance
 - ❑ Same backend (and pinout)

- ❑ **CALOROC1C** for Si/LAr detectors:
 - ❑ Based on CMS Si HGCROC with EIC readout

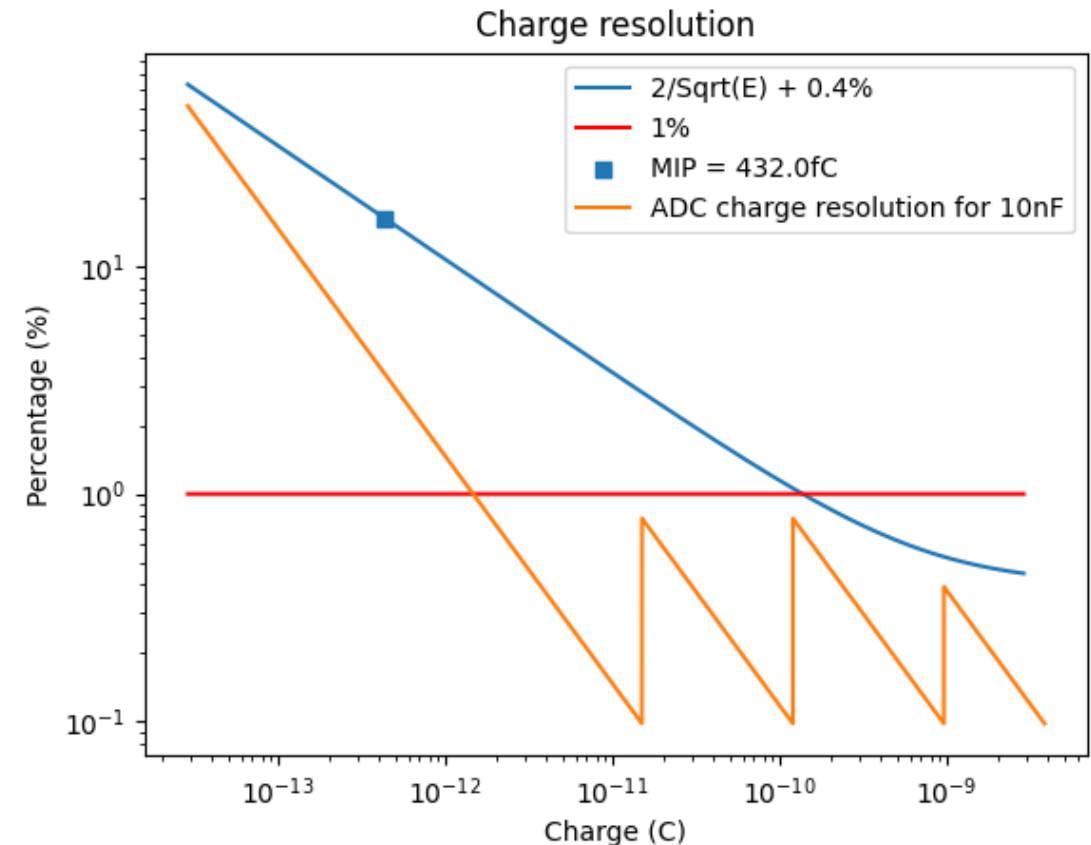
- ❑ All CALOROCs share the same backend + RadHard
 - ❑ We ~**150 ASICs per each flavor**
 - ❑ GIT for back-end designers
 - ❑ Datasheet available soon

- ❑ Submission process started with IMEC (May 19)
 - ❑ Paperwork ongoing on CERN side in parallel of the submission



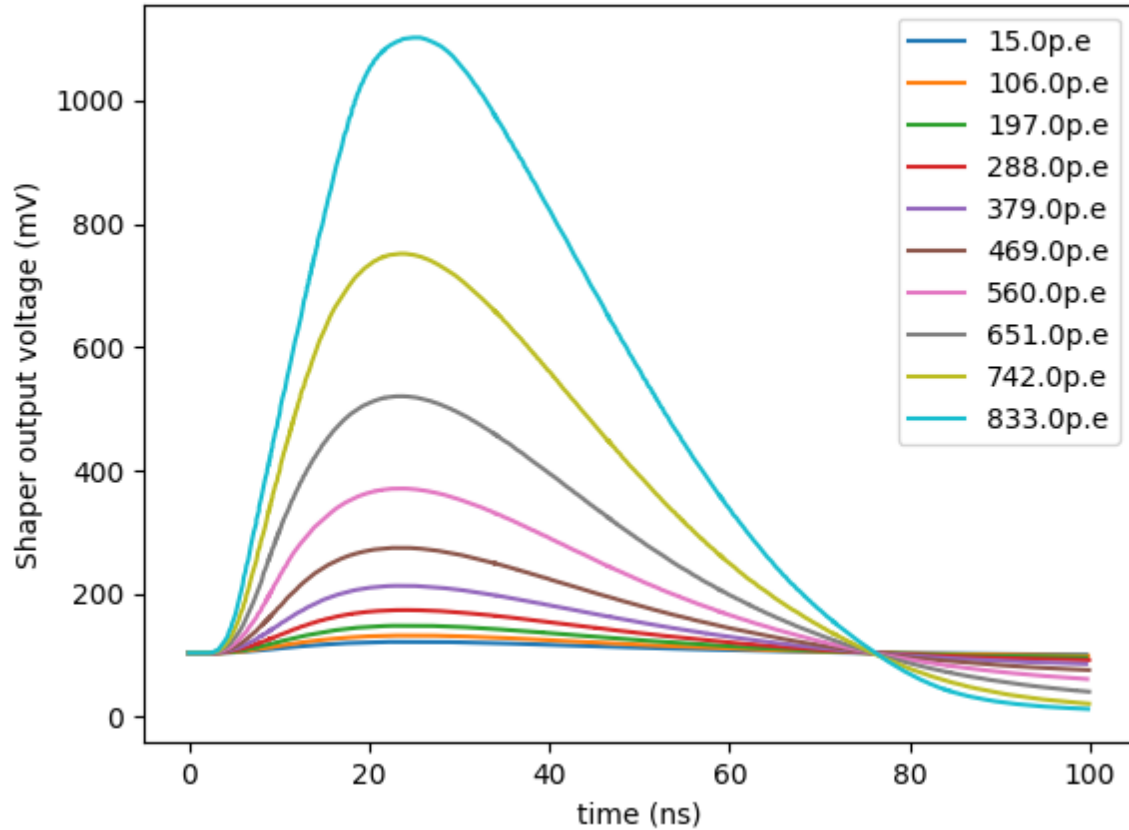
CALOROCs are targeted to include all features + radiation hardness on the first submission

- ❑ The SiPM configuration has a direct impact on the dynamic range
 - ❑ The highest measurable charge is determined by the SiPM input capacitance.
 - ❑ The ratio between the highest and the lowest measurable charge is constant.
- ❑ 10b resolution and 16b dynamic range
 - ❑ With a 10b ADC and 4 gains (2b) we have a resolution of 16b
 - ❑ The measured charge is in the format of $10b * GainRatio^{2b}$
 - ❑ The gain ratio can be adjusted to increase the dynamic range in exchange for a lower resolution.
 - ❑ Using the highest resolution the dynamic range is 70k
 - ❑ Supposing $1MeV = 1p.e$ for the 4 SiPM setup this should give us a dynamic range of 1.5MeV (noise floor) to 100GeV

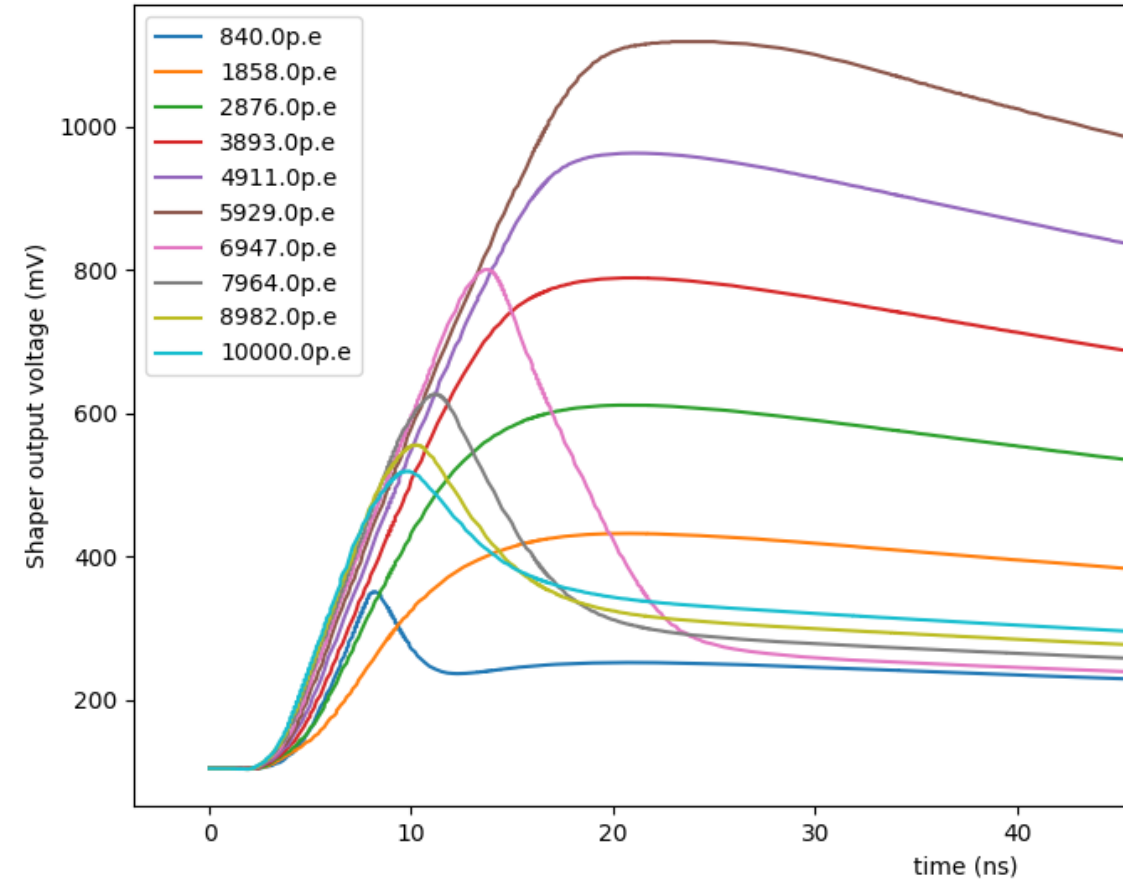


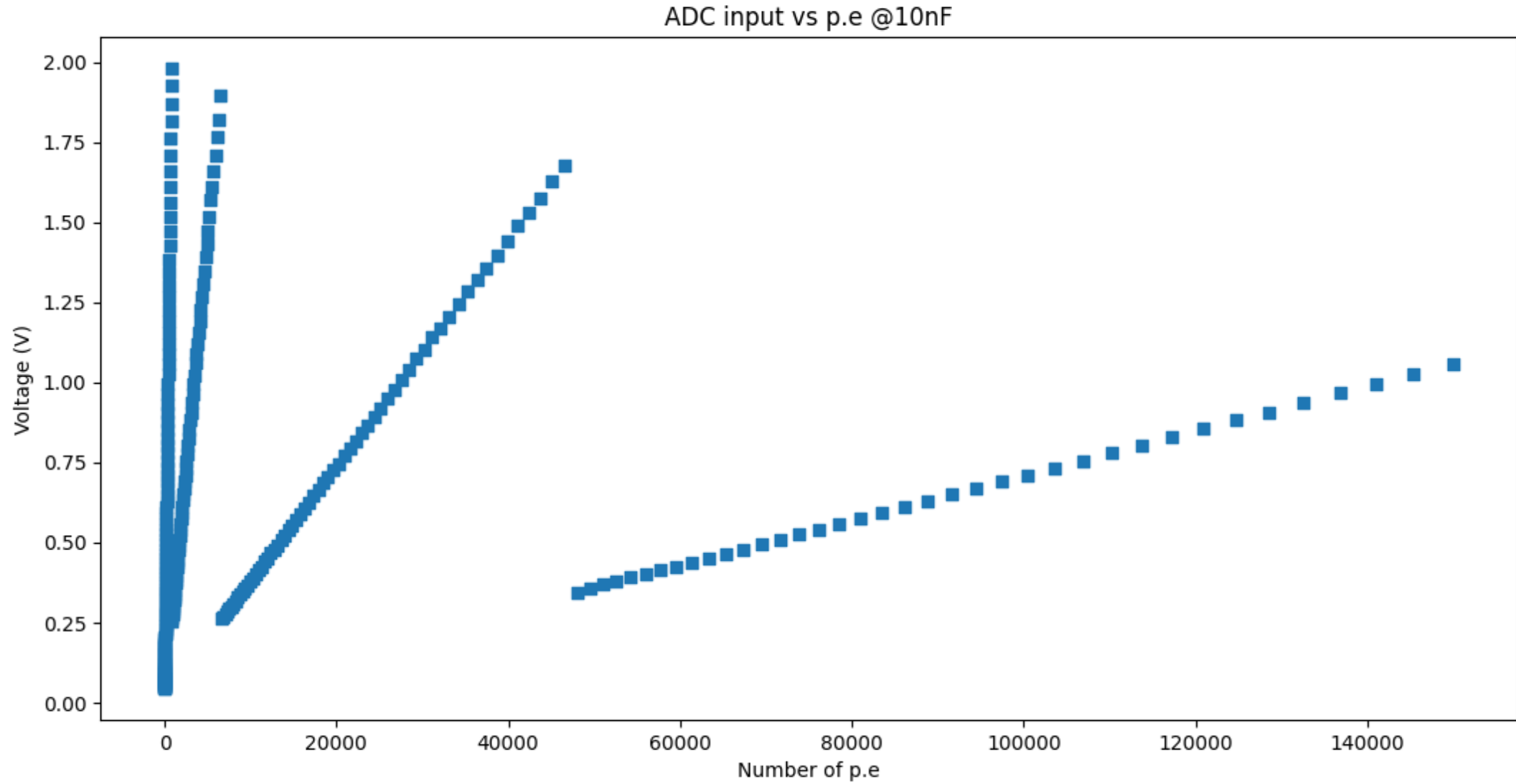
- Waveform for HG on the left + gain switching on the right:
 - Example with Cd of 10 nF

Waveform for high gain shaper's output @10nF configuration



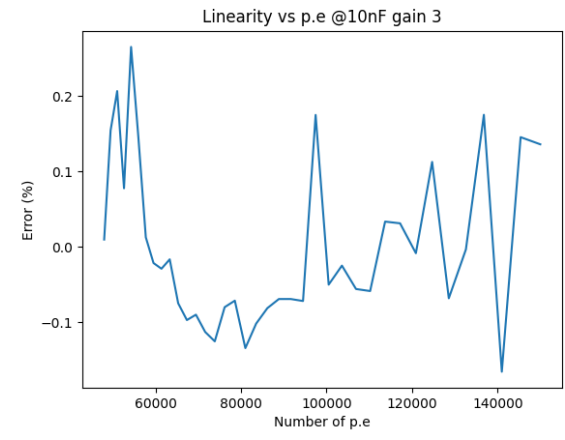
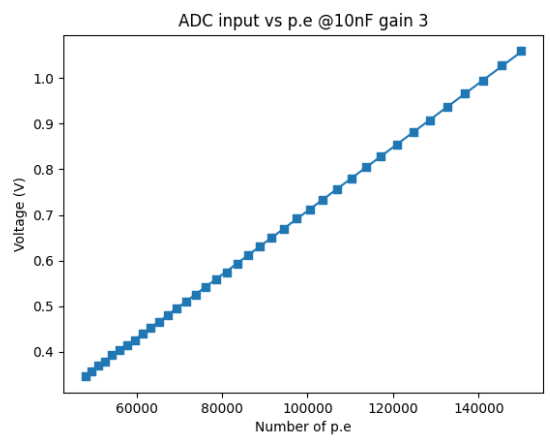
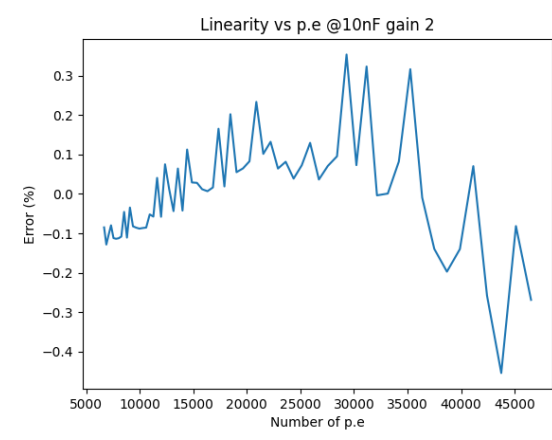
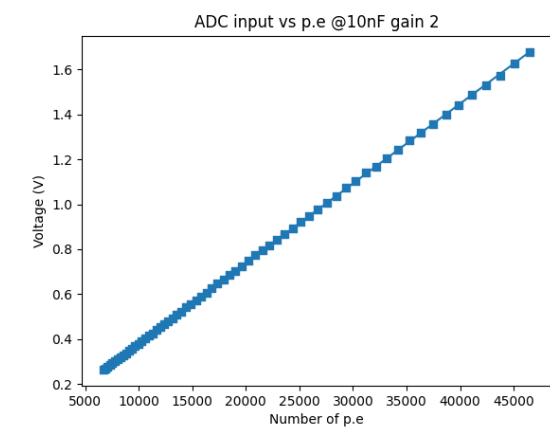
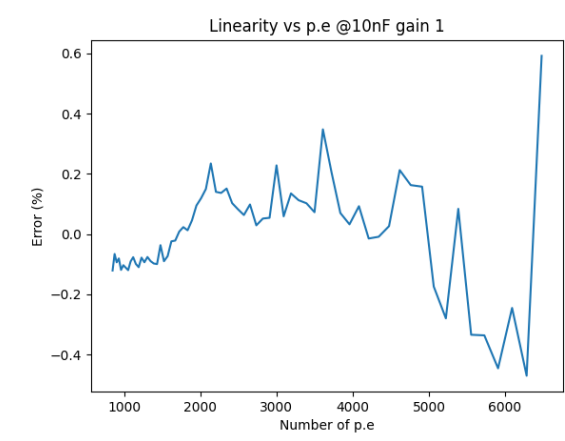
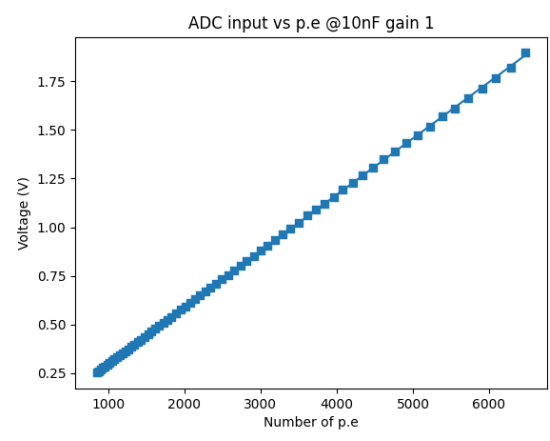
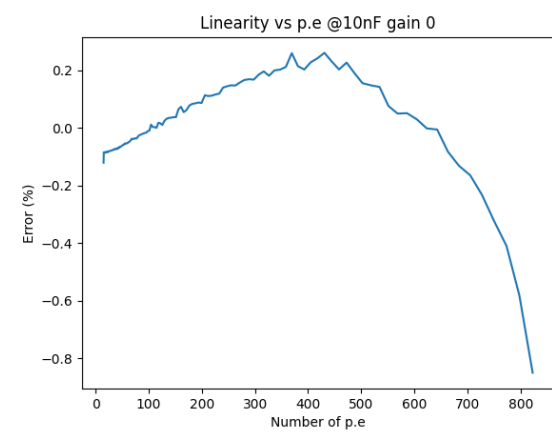
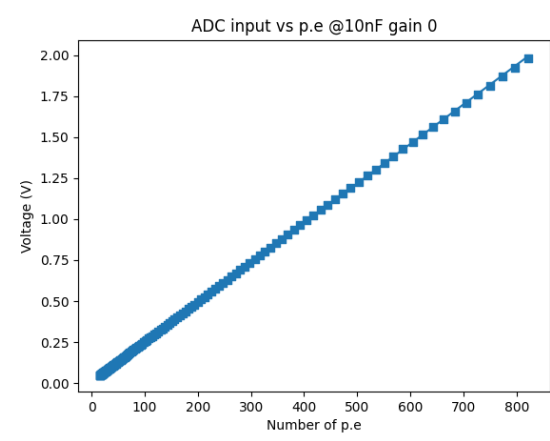
Waveform for medium gain shaper's output





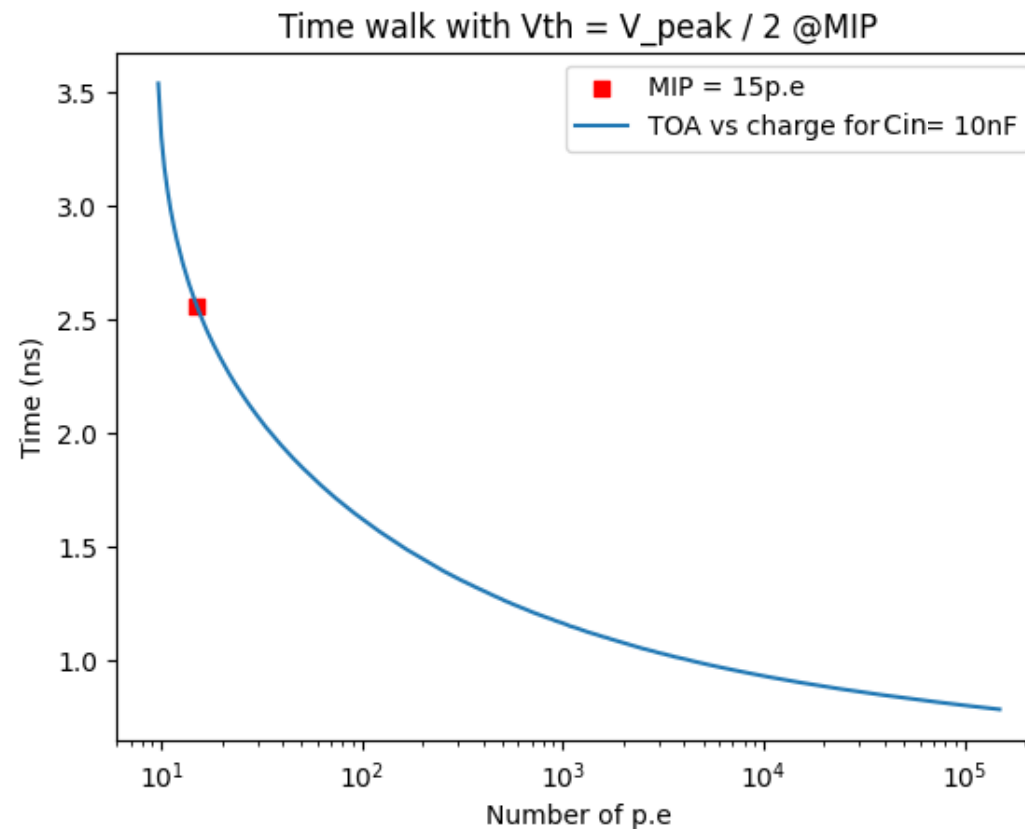
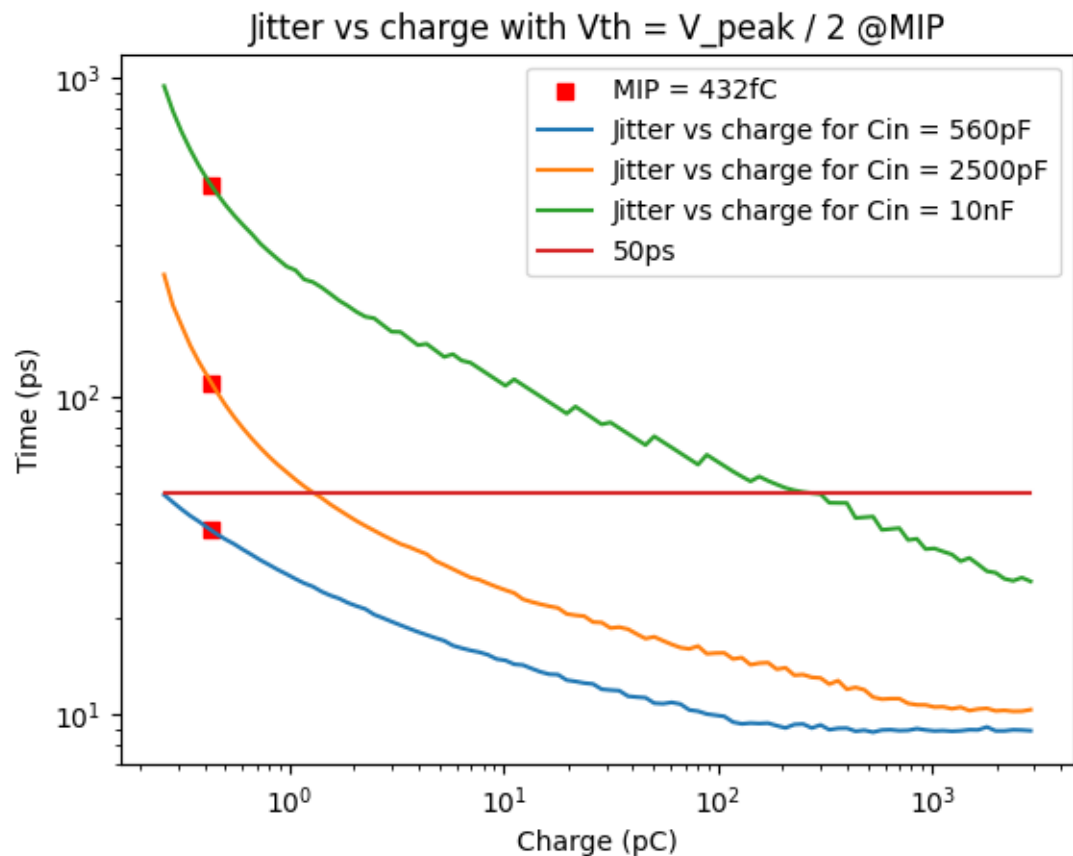
CALOROC1B: Linearity error

Less than 1% linearity error



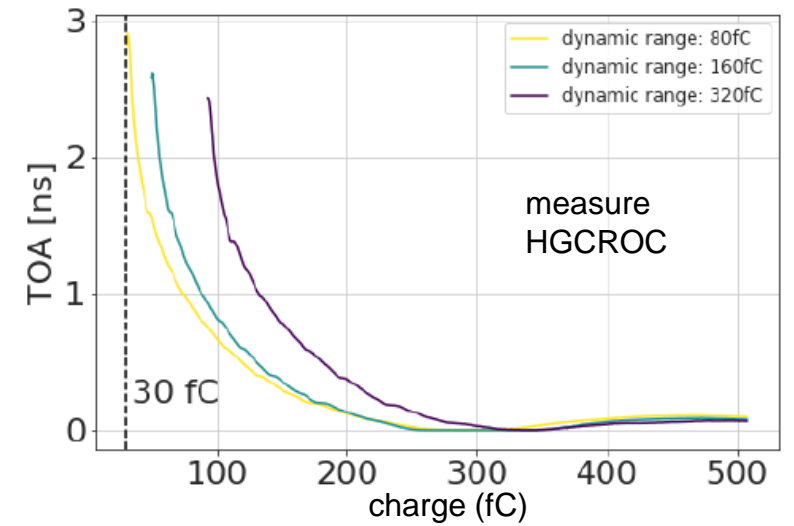
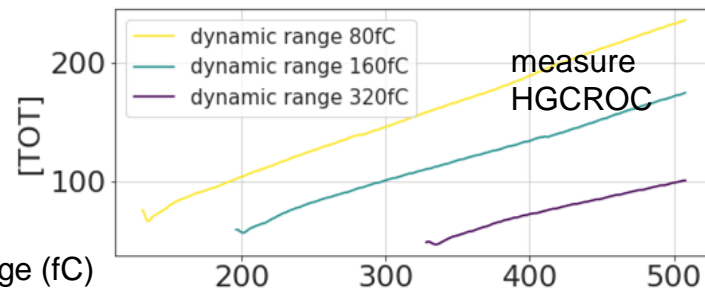
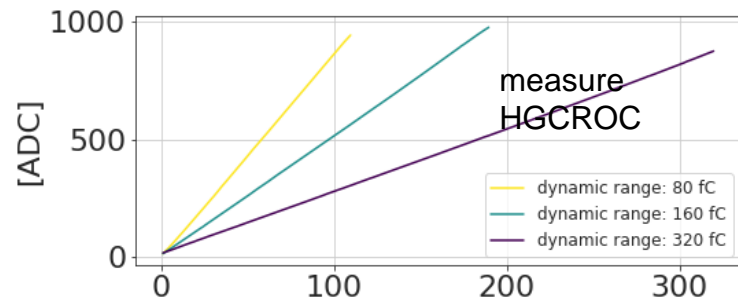
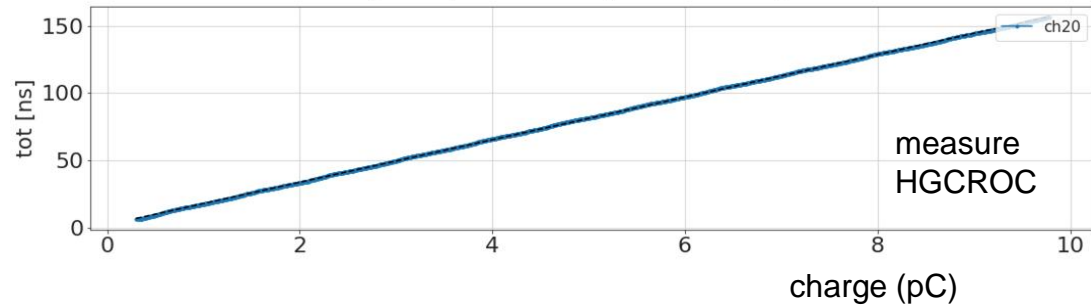
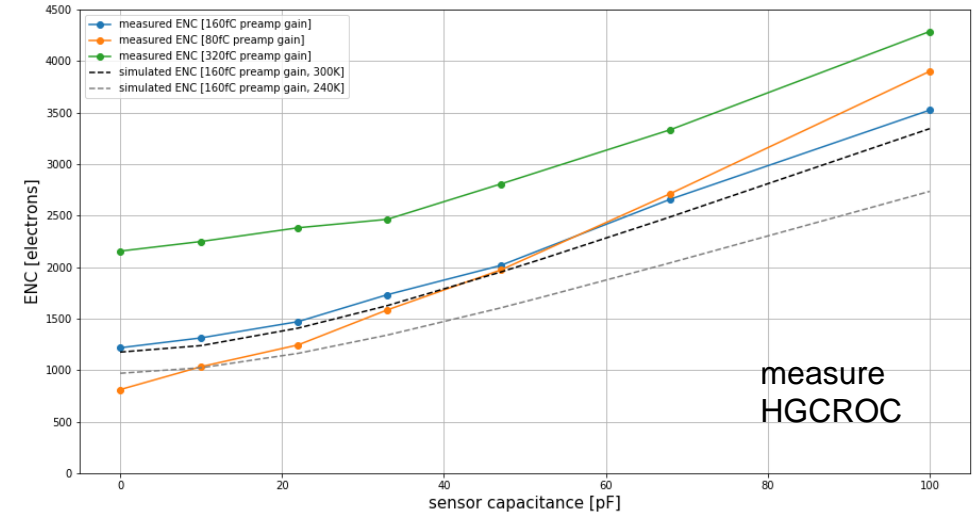
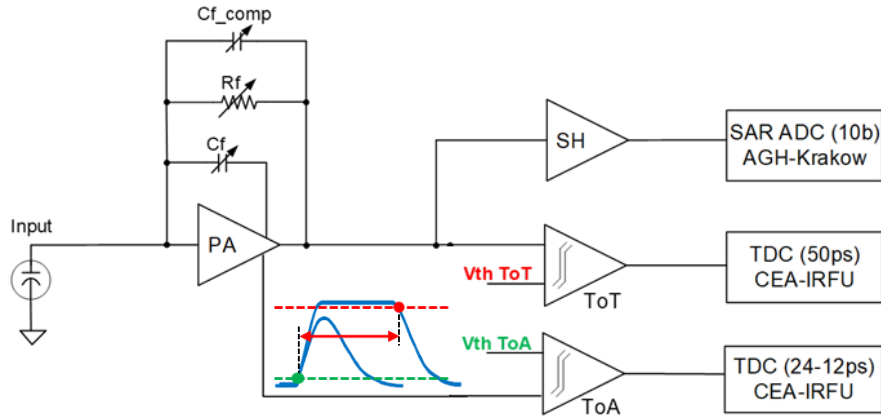
CALOROC1B: Timing precision

- ❑ Simulated time jitter goes down to 20 ps with < 500 ps for a MIP of 432fC @Cin=10nF
- ❑ Time walk is below ~2,5 ns



☐ Reuse of analog front-end based on ADC/TOT and TOA: fully characterized *

☐ 15 mW per channel / Radiation performance / Si up to 100 pF



* TWEPP 2023 <https://doi.org/10.1088/1748-0221/19/04/C04005>

❑ CALOROC1C will

- update its back-end (readout streaming)
- slow down the shaping from 25ns to 100ns

